

2017

A

2009			2016	
	1,109	4,335.5		
21.50%				
		2016		
			1,644.3	24.1%
			2016	
25.1%	1,126.9		1,564.3	13%
2017	1-6		2,201.3	19.1%
		21.1%	830.1	25.6%
	571.2		800.1	13.2%
		IC		

2

CSP

WLP

TSV

2025

3D

3

40% 2010
6% 2014 10%
2012 1,000
2016 1,564.3

FC/QFN

BGA

LGA

3D-TSV

2

1

Fan-out eWLB WLCSP SiP BUMP PoP

2017 9 30

2,681

1,740

FBGA PBGA

P-SiP IC

QFN

FC-BGA

2

MEMS

FBGA

3

IC

3

173,492

169,498

3,994

4

24,181

7.52

10.74%

5

78

6

[2017]69

201732028100415

1

Bumping WLCSP

82

Bumping 47

3

2

1

2003

6

3202851600839

[2016]71

1

108,000

2

1

2014 2015 2016 2017 9

63.12% 73.83% 77.55% 70.12%

2015

2017 9 30 2016 12 31 2015 12 31 2014

12 31

		2017 9 30	2016 12 31	2015 12 31	2014 12 31
002185.SZ		33.49%	28.29%	25.22%	39.28%
002156.SZ		46.94%	45.18%	42.56%	40.22%
603005.SH		15.13%	13.47%	17.55%	23.25%
		31.85%	28.98%	28.44%	34.25%
600584.SH		70.12%	77.55%	73.83%	63.12%

